



OKI Semiconductor

FEDR27T6402G-02-03 Issue Date: Jul. 9, 2004

MR27T6402G

 $4\text{M-Word} \times 16\text{-Bit or } 8\text{M-Word} \times 8\text{-Bit } P2ROM$

FEATURES

- \cdot 4,194,304-word \times 16-bit / 8,388,608-word \times 8-bit electrically switchable configuration
- · 2.7 V to 3.6 V power supply

· Access time 90 ns MAX

· Operating current 20 mA MAX (5MHz)

· Standby current 10 µA MAX

- · Input/Output TTL compatible
- · Three-state output

PACKAGES

- MR27T6402G-xxxMA
 44-pin plastic SOP (SOP44-P-600-1.27-K)
- \cdot MR27T6402G-xxxTP

44-pin plastic TSOP (TSOP II 44-P-400-0.80-K)

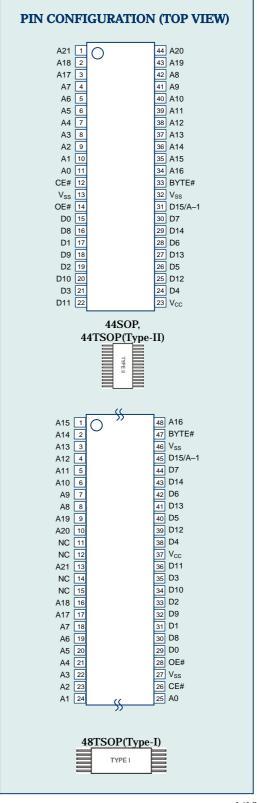
· MR27T6402G-xxxTN

48-pin plastic TSOP (TSOP I 48-P-1220-0.50-1K)

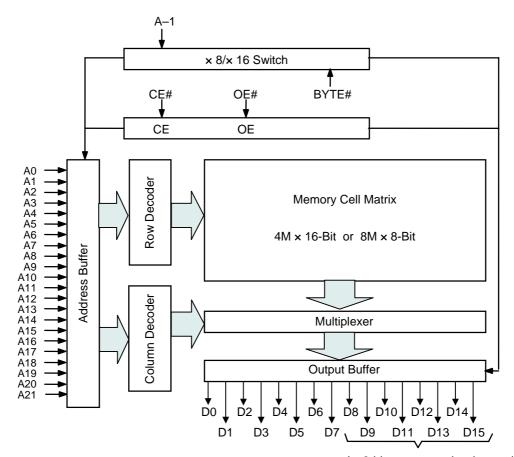
P2ROM ADVANCED TECHNOLOGY

P2ROM stands for Production Programmed ROM. This exclusive Oki technology utilizes factory test equipment for programming the customers code into the P2ROM prior to final production testing. Advancements in this technology allows production costs to be equivalent to MASKROM and has many advantages and added benefits over the other non-volatile technologies, which include the following;

- Short lead time, since the P2ROM is programmed at the final stage of the production process, a large P2ROM inventory "bank system" of un-programmed packaged products are maintained to provide an aggressive lead-time and minimize liability as a custom product.
- No mask charge, since P2ROMs do not utilize a custom mask for storing customer code, no mask charges apply.
- No additional programming charge, unlike Flash and OTP that require additional programming and handling costs, the P2ROM already has the code loaded at the factory with minimal effect on the production throughput. The cost is included in the unit price.
- Custom Marking is available at no additional charge.
- Pin Compatible with Mask ROM and some FLASH products.



BLOCK DIAGRAM



In 8-bit output mode, these pins are placed in a high-Z state and pin D15 functions as the A-1 address pin.

PIN DESCRIPTIONS

Pin name	Functions
D15 / A-1	Data output / Address input
A0 to A21	Address inputs
D0 to D14	Data outputs
CE#	Chip enable input
OE#	Output enable input
BYTE#	Word / Byte select input
Vcc	Power supply voltage
V _{SS}	Ground
NC	No connect

FUNCTION TABLE

Mode	CE#	OE#	BYTE#	V _{CC}	D0 to D7	D8 to D14	D15/A-1	
Read (16-Bit)	L	L	Н		D _{оит}			
Read (8-Bit)	L	L	L		D _{OUT}	Hi–Z	L/H	
O. d d. dia abda		Н	Н	3.0 V		LI: 7		
Output disable	_		L			Hi–Z	*	
Standby	Н	*	Н		Hi–Z			
			L				*	

^{*:} Don't Care (H or L)

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Value	Unit
Operating temperature under bias	Та		0 to 70	°C
Storage temperature	Tstg	_	-55 to 125	°C
Input voltage	VI		-0.5 to V _{CC} +0.5	V
Output voltage	Vo	relative to V _{SS}	-0.5 to V _{CC} +0.5	V
Power supply voltage	V _{CC}		–0.5 to 5	V
Power dissipation per package	P_D	Ta = 25°C	1.0	W
Output short circuit current	los	_	10	mA

RECOMMENDED OPERATING CONDITIONS

 $(Ta = 0 \text{ to } 70^{\circ}C)$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
V _{CC} power supply voltage	V _{CC}		2.7		3.6	V
Input "H" level	V _{IH}	$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$	2.2	_	V _{CC} +0.5*	V
Input "L" level	V _{IL}		-0.5**	_	0.6	V

Voltage is relative to V_{SS} .

- * : Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.
- $**: \mbox{-1.5V(Min.)}$ when pulse width of undershoot is less than 10ns.

PIN CAPACITANCE

 $(V_{CC} = 3.0 \text{ V}, \text{Ta} = 25^{\circ}\text{C}, \text{f} = 1 \text{ MHz})$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input	C _{IN1}	V _I = 0 V	_	_	8	
BYTE#	C _{IN2}	V ₁ = 0 V	_		200	pF
Output	C _{OUT}	$V_O = 0 V$	_	_	10	

ELECTRICAL CHARACTERISTICS

DC Characteristics

 $(V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}, \text{ Ta} = 0 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input leakage current	ILI	$V_I = 0$ to V_{CC}	_	_	10	μА
Output leakage current	I _{LO}	$V_O = 0$ to V_{CC}	_	_	10	μА
V _{CC} power supply current	Iccsc	CE# = V _{CC}	_	_	10	μΑ
(Standby)	I _{CCST}	CE# = V _{IH}	_	_	1	mA
V _{CC} power supply current	1	$CE\# = V_{IL}, OE\# = V_{IH}$			20	mA
(Read)	I _{CCA}	f=5MHz			20	IIIA
Input "H" level	V_{IH}	_	2.2	_	V _{CC} +0.5*	V
Input "L" level	V _{IL}	_	-0.5**	_	0.6	V
Output "H" level	V _{OH}	$I_{OH} = -1 \text{ mA}$	2.4	_	_	V
Output "L" level	V _{OL}	I _{OL} = 2 mA	_	_	0.4	V

Voltage is relative to V_{SS} .

- * : Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.
- **: -1.5V(Min.) when pulse width of undershoot is less than 10ns.

AC Characteristics

 $(V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}, \text{Ta} = 0 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Condition	Min.	Max.	Unit
Address cycle time	t _C	_	90		ns
Address access time	t _{ACC}	CE# = OE# = V _{IL}	_	90	ns
CE# access time	t _{CE}	OE# = V _{IL}	_	90	ns
OE# access time	t _{OE}	CE# = V _{IL}	_	30	ns
Output disable time	t _{CHZ}	OE# = V _{IL}	0	30	ns
Output disable time	t _{OHZ}	CE# = V _{IL}	0	25	ns
Output hold time	t _{OH}	CE# = OE# = V _{IL}	0	_	ns

Measurement conditions

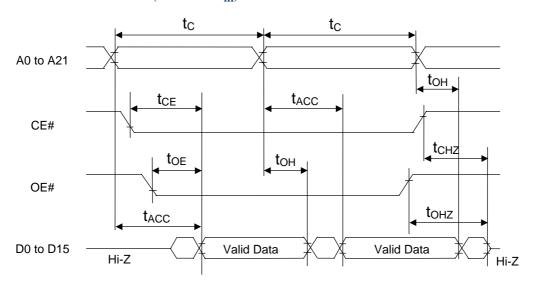
Input signal level ------0 V/2.7 V Input timing reference level------1/2Vcc Output load -----50 pF Output timing reference level -----1/2Vcc

Output load

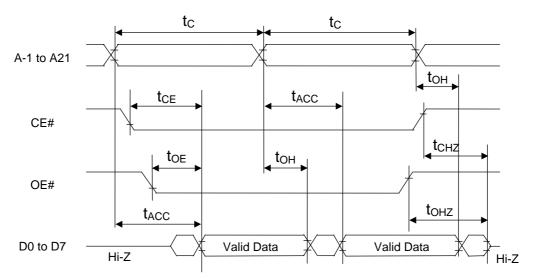


TIMING CHART (READ CYCLE)

16-BIT READ MODE (BYTE# = V_{IH})

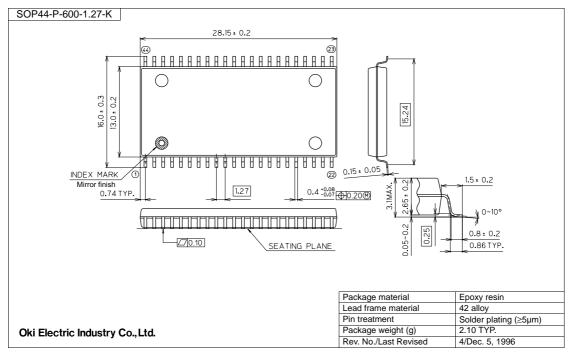


8-BIT READ MODE (BYTE# = V_{IL})



PACKAGE DIMENSIONS

(Unit: mm)

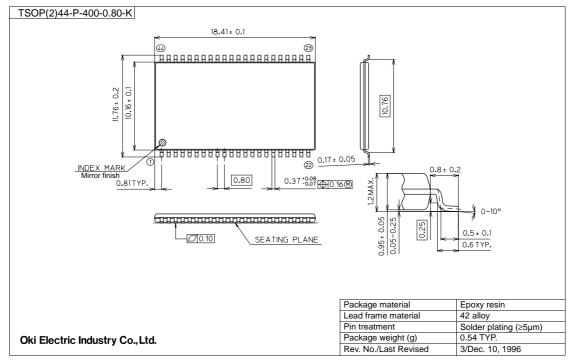


Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

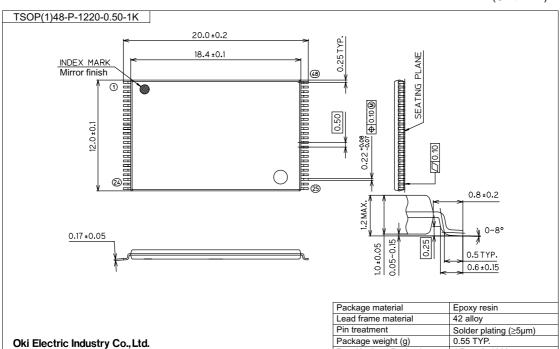




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(Unit: mm)

1/Dec. 2, 1999

Rev. No./Last Revised

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REVISION HISTORY

Document		Pa	ge	
No.	Date	Previous Edition	Current Edition	Description
FEDR27T6402G-02-01	Oct., 2001	-	-	Final edition 1
		1	1	Change 48TSOP(1) package code to -1K
FEDR27T6402G-02-02	Jun. 4, 2003	1, 4	1, 4	Unify I _{CCA} condition into f=5MHz
FEDR27T6402G-02-03	Jul. 9, 2004	3	3	Add P _D condition and I _{OS} = 10mA

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